

**REMARKS**

Claims 1-14 are pending in this application. Applicant appreciates the Office Action's indication that claim 12 is allowed and claims 3 and 4 contain allowable subject matter. It is noted that claim 3 is an independent claim. Thus, claims 3 and 4 should also have been allowed.

By this Amendment, claim 1 is amended for better clarity. Claims 15-22 are canceled due to the finality of the Restriction Requirement.

Reconsideration of the application is respectfully requested.

The Examiner is respectfully requested to acknowledge receipt of the Claim for Priority filed May 21, 2004.

The Office Action rejects claim 1 under 35 U.S.C. §102(b) over U.S. Patent 6,587,353 to Sumikawa et al. ("Sumikawa"). This rejection is respectfully traversed.

The Office Action asserts that Sumikawa discloses all elements recited in claim 1. However, Sumikawa does not disclose or suggest terminal electrodes that are disposed on a substrate at locations of the substrate based on a stress distribution that works on the substrate, as recited in claim 1.

In particular, Sumikawa discloses a device in which resin members 5 are formed beneath electrodes 8 to relax thermal stress. See Fig. 2 and col. 7, lines 37-48. Sumikawa does not disclose or suggest a stress distribution that works on a substrate. Therefore, Sumikawa does not disclose or suggest terminal electrodes that are disposed on a substrate at locations of the substrate based on a stress distribution that works on the substrate, as recited in claim 1.

Furthermore, Sumikawa does not disclose or suggest terminal electrodes that are disposed on the substrate at locations of the substrate based on a stress distribution that works on the substrate, as recited in claim 1. In particular, Sumikawa discloses an arrangement

between rewiring pattern 6 and connecting electrode 8. See Fig. 1 and col. 8, lines 10-20. Sumikawa discloses such an arrangement based on a crossing angle between the rewiring pattern 6 and the connecting electrode 8. See col. 8, lines 37-49. Sumikawa does not disclose or suggest locations of terminal electrodes on a substrate. Therefore, Sumikawa does not disclose or suggest terminal electrodes that are disposed on the substrate at locations of the substrate based on a stress distribution that works on the substrate, as recited in claim 1.

For any or all of the above reasons, Sumikawa does not disclose each and every element recited in claim 1. Accordingly, withdrawal of the rejection of claim 1 under 35 U.S.C. §102(b) is respectfully requested.

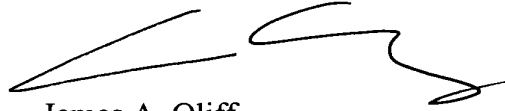
The Office Action rejects claims 2, 5-11, 13 and 14 under 35 U.S.C. §103(a) over Sumikawa and JPA2004-281470 ("JP reference"). This rejection is respectfully traversed.

In particular, the JP reference has a filing date of March 12, 2003, which is later than the January 16, 2003 filing date of the priority document of the present application. Thus, the JP reference does not qualify as a prior art reference. An accurate translation of the priority document JP2003-007769 is enclosed to perfect the Claim for Priority filed May 21, 2004. Accordingly, withdrawal of the rejection of claims 2, 5-11, 13 and 14 under 35 U.S.C. §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-14 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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Attachment:

Translation of Priority Document JP2003-007769

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